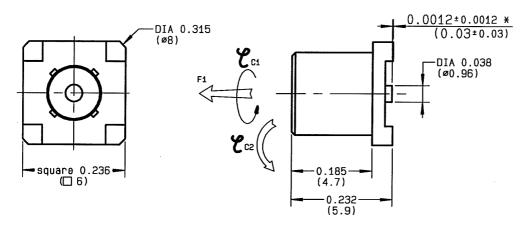
R113.424.000

Series: MCX

\*set back of c. contact from body (Retrait du c. central/ au corps)



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BRASS BERYLLIUM COPPER - PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.5 OVER NICKEL 2

**Issue:** 0422 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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#### **PACKAGING**

### Standard Unit Other 100 'W' option Contact us

#### **SPECIFICATION**

#### **ELECTRICAL CHARACTERISTICS**

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-6} \;\; \text{GHz} \end{array}$ 

VSWR 1.05 + 0.050 x F(GHz) Maxi

Insertion loss 0.03 VF(GHz) Maxi

RF leakage - ( NA - F(GHz)) dB Maxi Voltage rating 335 Veff Maxi

Dielectric withstanding voltage 1000 Veff mini Insulation resistance 1000 M $\Omega$  mini

#### **ENVIRONMENTAL**

Operating temperature -55/+155 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

#### **OTHERS CHARACTERISTICS**

Assembly instruction

Others:

FORCE F1:90N-TORQUES C1:45Ncm-C2:80Ncm

#### **MECHANICAL CHARACTERISTICS**

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0.620** g

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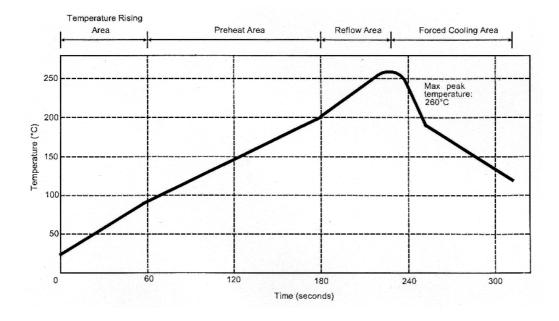
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#### **SOLDER PROCEDURE**

- Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microms mini. ( .006 inch mini ). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Aspiration port (see page 4) centered into body and push against it. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
- Soldering by infra-red reflow. Below please find ,the typical profile to use.
- Cleaning of printed circuit boards.
- Verification of solder joints and position of the component by visual inspection.

#### **TEMPERATURE PROFILE**



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

**Issue:** 0422 D

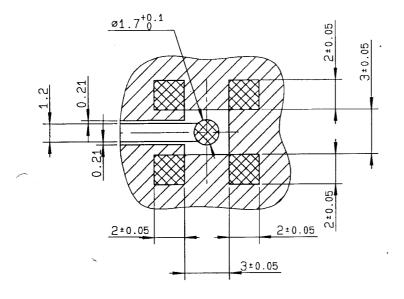
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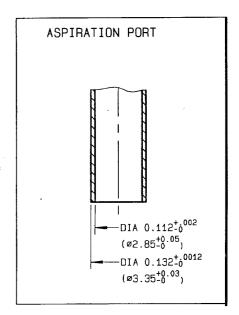
necessary.



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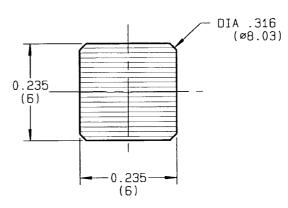


COPLANAR LINE
Pattern and signal are on the same side
Thickness of PCB: .063 (1.6 mm)
The material of PCB is the epoxy resin
of glass fabrics bacs.(Er = 4.8)
The solder resist should be printed
exept for the land pattern on the PCB.

Pattern

Land for solder paste

### SHADOW OF MCX RECEPTACLE FOR VIDEO CAMERA



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